

**REMARKS/ARGUMENTS**

The foregoing amendment is presented to make certain that all aspects of the disclosed invention are adequately claimed. Thus, Claims 12-16 are directed to the moldable epoxy resin composition for packaging a semiconductor element.

Claims 20 and 21 are directed to the two package composition for encapsulating a semiconductor device comprising the moldable epoxy resin composition as one component and the second component being the curing accelerator which is then mixed with the resin composition shortly before encapsulating the semiconductor element.

The application has also been amended on page 18 to conform with the correct description of Figure 1.

No new matter is presented.

An amended version of Figure 1 is furnished herewith showing the correction to add the index number "7" which indicates the hole for inserting the push pull gauge.

Examination on the merits is awaited.

Respectfully submitted,

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